

ABSTRACT

A method is provided to enhance the connection reliability in three-dimensional mounting while considering the warping of packages. Opening diameters of the openings provided corresponding to protruding electrodes, respectively, are set so as to gradually decrease from the central portion toward the outer peripheral portion of a carrier substrate, and the opening diameters of openings provided corresponding to the protruding electrodes, respectively, are set so as to gradually decrease from the central portion toward the outer peripheral portion of another carrier substrate.